# XP06213 (XP6213)

## Silicon NPN epitaxial planer transistor

For switching/digital circuits

#### Features

- Two elements incorporated into one package. (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

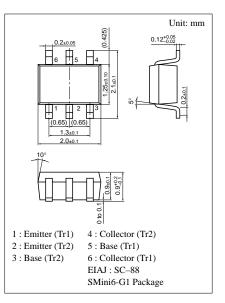
### Basic Part Number of Element

• UNR1213  $\times$  2 elements

Parameter		Symbol	Ratings	Unit
Rating of element	Collector to base voltage	V <sub>CBO</sub>	50	V
	Collector to emitter voltage	V <sub>CEO</sub>	50	V
	Collector current	I <sub>C</sub>	100	mA
Overall	Total power dissipation	P <sub>T</sub>	150	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T <sub>stg</sub>	-55 to +150	°C

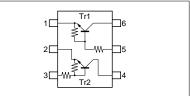
#### Absolute Maximum Ratings (Ta=25°C)

Electrical Characteristics (Ta=25°C)



#### Marking Symbol: 8W

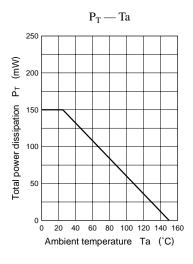
#### Internal Connection

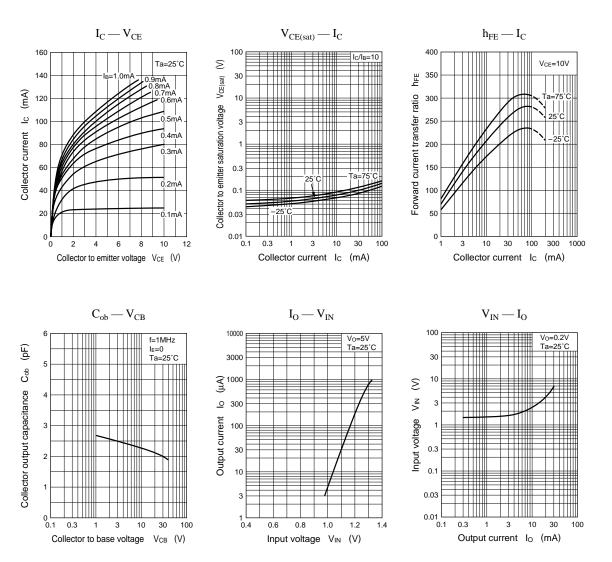


#### Parameter Symbol Conditions max Unit min typ Collector to base voltage V<sub>CBO</sub> $I_{C} = 10 \mu A, I_{E} = 0$ 50 V V<sub>CEO</sub> $I_{C} = 2mA, I_{B} = 0$ 50 V Collector to emitter voltage $V_{CB} = 50V, I_E = 0$ 0.1 μA I<sub>CBO</sub> Collector cutoff current $V_{CE} = 50V, I_B = 0$ 0.5 I<sub>CEO</sub> μΑ Emitter cutoff current $I_{EBO}$ $V_{EB} = 6V, I_C = 0$ 0.1 mA Forward current transfer ratio $V_{CE} = 10V, I_C = 5mA$ 80 h<sub>FE</sub> $V_{CE} = 10V, I_C = 5mA$ hFE (small/large)\*1 0.5 0.99 Forward current transfer h<sub>FE</sub> ratio Collector to emitter saturation voltage $I_{C} = 10mA, I_{B} = 0.3mA$ 0.25 V V<sub>CE(sat)</sub> Output voltage high level $V_{CC} = 5V, V_B = 0.5V, R_L = 1k\Omega$ 4.9 V V<sub>OH</sub> $V_{CC} = 5V, V_B = 3.5V, R_L = 1k\Omega$ V Output voltage low level VOL 0.2 Transition frequency $\mathbf{f}_{\mathrm{T}}$ $V_{CB} = 10V, I_E = -2mA, f = 200MHz$ 150 MHz Input resistance $R_1$ -30% 47 +30% kΩ Resistance ratio 0.8 1.0 1.2 $R_{1}/R_{2}$

\*1 Ratio between 2 elements

Note) The Part number in the Parenthesis shows conventional part number.





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